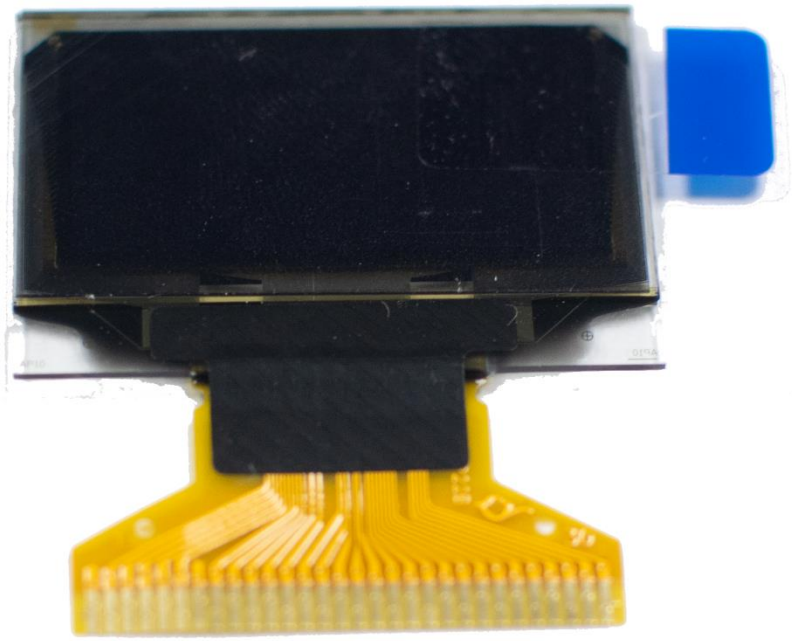
DisplayModule



DM-OLED096-624PANEL

0.96” 128 X 64 WHITE GRAPHIC OLED DISPLAY MODULE – MCU、I2C、SPI

Contents

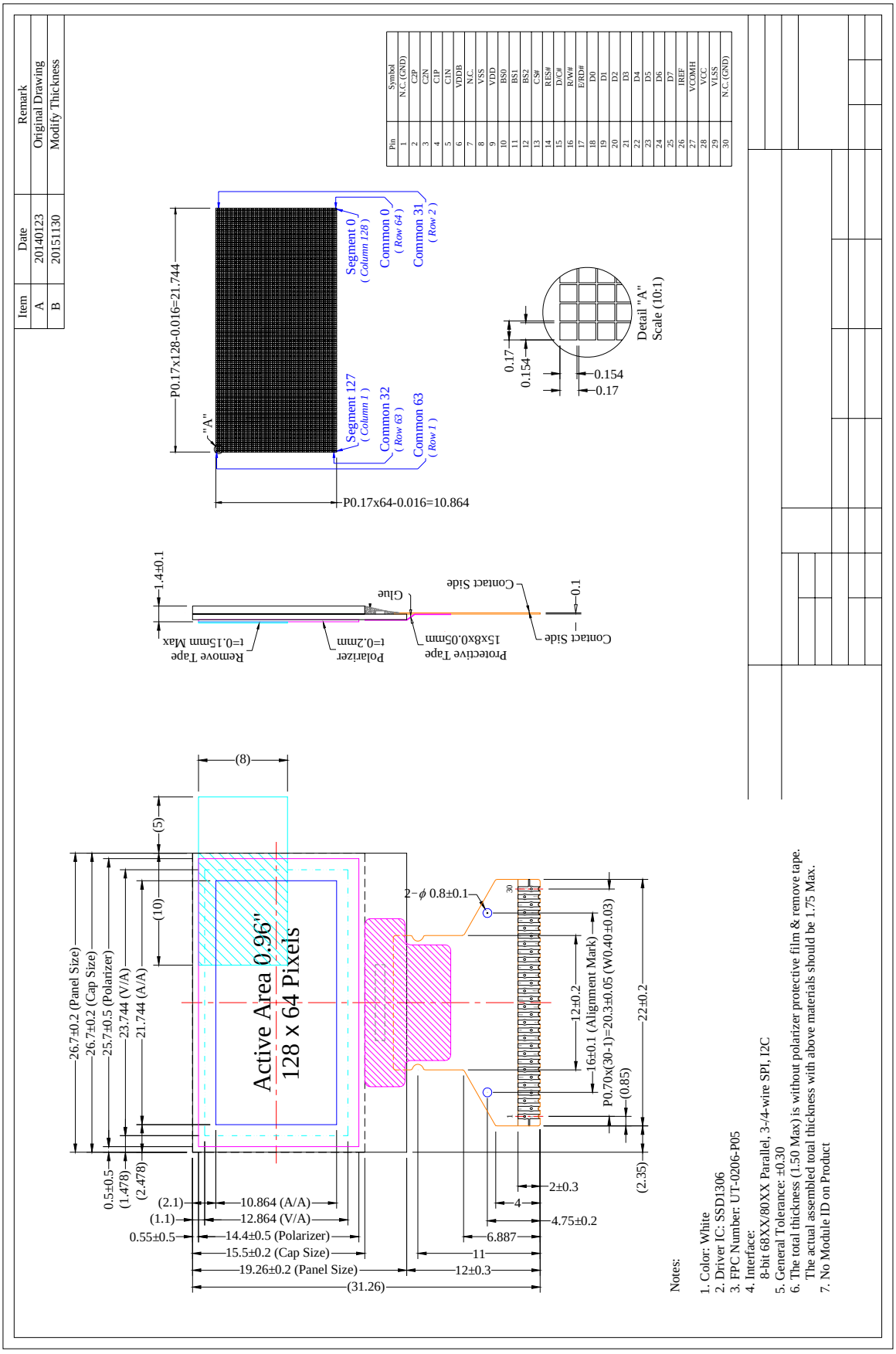
1 Revision History

Date	Changes
2022-08-19	First release

2 Main Features

Item	Specification	Unit
Diagonal Size	0.96"	inch
Display Mode	Passive Matrix OLED	-
Display Colors	Monochrome (White)	Colors
Resolution	128 x 64	pixel
Controller IC	SSD1306	-
Duty	1/64	duty
Interface	8-bit 68XX/80XX Parallel,3/4-wire SPI,I2C	-
Active Area	21.744 x 10.864	mm
Module Dimension	26.70 x 19.26 x 1.45	mm
Weight	1.54	g

1.4 Mechanical Drawing



1.5 Pin Definition

<table>
<tr><th>Pin Number</th><th>Symbol</th><th>I/O</th><th>Function</th></tr>
<tr><td colspan="4">Power Supply</td></tr>
<tr><td>9</td><td>VDD</td><td>P</td><td>Power Supply for Logic
This is a voltage supply pin. It must be connected to external source.</td></tr>
<tr><td>8</td><td>VSS</td><td>P</td><td>Ground of Logic Circuit
This is a ground pin. It acts as a reference for the logic pins. It must be connected to external ground.</td></tr>
<tr><td>28</td><td>VCC</td><td>P</td><td>Power Supply for OEL Panel
This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and V_{SS} when the converter is used. It must be connected to external source when the converter is not used.</td></tr>
<tr><td>29</td><td>VLSS</td><td>P</td><td>Ground of Analog Circuit
This is an analog ground pin. It should be connected to V_{SS} externally.</td></tr>
<tr><td colspan="4">Driver</td></tr>
<tr><td>26</td><td>IREF</td><td>I</td><td>Current Reference for Brightness Adjustment
This pin is segment current reference pin. A resistor should be connected between this pin and V_{SS}. Set the current at 12.5μA maximum.</td></tr>
<tr><td>27</td><td>VCOMH</td><td>O</td><td>Voltage Output High Level for COM Signal
This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and V_{SS}.</td></tr>
<tr><td colspan="4">DC/DC Converter</td></tr>
<tr><td>6</td><td>VDDB</td><td>P</td><td>Power Supply for DC/DC Converter Circuit
his is the power supply pin for the internal buffer of the DC/DC voltage converter. It must be connected to external source when the converter is used. It should be connected to V when the converter is not used.</td></tr>
<tr><td>4 / 5
2 / 3</td><td>C1P / C1N
C2P / C2N</td><td></td><td>Positive Terminal of the Flying Inverting Capacitor
Negative Terminal of the Flying Boost Capacitor
The charge-pump capacitors are required between the terminals. They must be floated when the converter is not used.</td></tr>
<tr><td colspan="4">Interface</td></tr>
<tr><td>10
11
12</td><td>BS0
BS1
BS2</td><td>I</td><td>Communicating Protocol Select
These pins are MCU interface selection input. See the following table:
<table>
<tr><th></th><th>BS0</th><th>BS1</th><th>BS2</th></tr>
<tr><td>I^2C</td><td>0</td><td>1</td><td>0</td></tr>
<tr><td>3-wire Serial</td><td>1</td><td>0</td><td>0</td></tr>
<tr><td>4-wire Serial</td><td>0</td><td>0</td><td>0</td></tr>
<tr><td>8-bit 68XX Parallel</td><td>0</td><td>0</td><td>1</td></tr>
<tr><td>8-bit 80XX Parallel</td><td>0</td><td>1</td><td>1</td></tr>
</table></td></tr>
<tr><td>14</td><td>RES#</td><td>I</td><td>Power Reset for Controller and Driver
This pin is reset signal input. When the pin is low, initialization of the chip is executed. Keep this pin pull high during normal operation.</td></tr>
<tr><td>13</td><td>CS#</td><td>I</td><td>Chip Select
This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.</td></tr>
<tr><td>15</td><td>D/C#</td><td>I</td><td>Data/Command Control
This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register.
When the pin is pulled high and serial interface mode is selected, the data at SDIN will be interpreted as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I^2C mode, this pin acts as SA0 for slave address selection.
For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams.</td></tr>
<tr><td>17</td><td>E/RD#</td><td>I</td><td>Read/Write Enable or Read
This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low.
When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low.
When serial or I^2C mode is selected, this pin must be connected to V_{SS}.</td></tr>
</table>

1.5 Pin Definition (Continued)

Pin Number	Symbol	I/O	Function
Interface (Continued)			
16	R/W#	I	**Read/Write Select or Write** This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode. When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low. When serial or I^2C mode is selected, this pin must be connected to V_{SS}.
18~25	D0~D7	I/O	**Host Data Input/Output Bus** These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I^2C mode is selected, D2 & D1 should be tired together and serve as SDA_{out} & SDA_{in} in application and D0 is the serial clock input SCL. Unused pins must be connected to V_{SS} except for D2 in serial mode.
Reserve			
7	N.C.	-	**Reserved Pin** The N.C. pin between function pins is reserved for compatible and flexible design.
1, 30	N.C. (GND)	-	**Reserved Pin (Supporting Pin)** The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground as the ESD protection circuit.

2. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	V_{DD}	-0.3	4	V	1, 2
Supply Voltage for Display	V_{CC}	0	11	V	1, 2
Supply Voltage for DC/DC	V_{DDB}	-0.3	5	V	1, 2
Operating Temperature	T_{OP}	-40	70	°C	
Storage Temperature	T_{STG}	-40	85	°C	3
Life Time (120 cd/m^2)		10,000	-	hour	4

Note 1: All the above voltages are on the basis of "V_{SS} = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: The defined temperature ranges do not include the polarizer. The maximum withstood temperature of the polarizer should be 80 C.

Note 4: End of lifetime is specified as 50% of initial brightness reached. The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

3.1 Optics Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Brightness (V_{CC} Supplied Externally)	L_{br}	Note 8	100	120	-	cd/m^2
Brightness (V_{CC} Generated by Internal DC/DC)	*L_{br}*	*Note 12*	*70*	*90*	*-*	*cd/m^2*
C.I.E. (White)	(x) (y)	C.I.E. 1931	0.24 0.27	0.27 0.30	0.30 0.33	
Dark Room Contrast	CR		-	>10,000:1	-	
Viewing Angle			-	Free	-	degree

* Optical measurement taken at V_{DD} = 2.8V, V_{CC} = 9V or *V_{DD} = 2.8V, V_{DDB} = 3.5V, V_{CC} Generated by Internal DC/DC.*
Software configuration follows Section 4.5 Initialization.

3.2 DC Characteristics

3.2.1 V_{CC} Supplied Externally

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage for Logic	V_{DD}		1.65	2.8	3.3	V
Supply Voltage for Display (Supplied Externally)	V_{CC}	Note 5 (Internal DC/DC Disable)	8.5	9.0	9.5	V
High Level Input	V_{IH}		0.8×V_{DD}	-	V_{DD}	V
Low Level Input	V_{IL}		0	-	0.2×V_{DD}	V
High Level Output	V_{OH}	I_{OUT} = 100μA, 3.3MHz	0.9×V_{DD}	-	V_{DD}	V
Low Level Output	V_{OL}	I_{OUT} = 100μA, 3.3MHz	0	-	0.1×V_{DD}	V
Operating Current for V_{DD}	I_{DD}		-	180	300	μA
Operating Current for V_{CC} (V_{CC} Supplied Externally)	I_{CC}	Note 6	-	5.7	7.1	mA
		Note 7	-	8.5	10.6	mA
		Note 8	-	15.3	19.1	mA
Sleep Mode Current for V_{DD}	$I_{DD, SLEEP}$		-	1	5	μA
Sleep Mode Current for V_{CC}	$I_{CC, SLEEP}$		-	2	10	μA

Note 5: Brightness (L_{br}) and Supply Voltage for Display (V_{CC}) are subject to the change of the panel characteristics and the customer's request.
Note 6: V_{DD} = 2.8V, V_{CC} = 9.0V, 30% Display Area Turn on.
Note 7: V_{DD} = 2.8V, V_{CC} = 9.0V, 50% Display Area Turn on.
Note 8: V_{DD} = 2.8V, V_{CC} = 9.0V, 100% Display Area Turn on.

* Software configuration follows Section 4.5.1 Initialization.

3.2.2 V_{CC} Generated by Internal DC/DC Circuit

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage for Logic	V_{DD}		1.65	2.8	3.3	V
Supply Voltage for DC/DC	V_{DDB}	Internal DC/DC Enable	3.0	-	4.2	V
Supply Voltage for Display (Generated by Internal DC/DC)	V_{CC}	Note 9 (Internal DC/DC Enable)	7.0	7.5	8.0	V
High Level Input	V_{IH}		0.8×V_{DD}	-	V_{DD}	V
Low Level Input	V_{IL}		0	-	0.2×V_{DD}	V
High Level Output	V_{OH}	I_{OUT} = 100μA, 3.3MHz	0.9×V_{DD}	-	V_{DD}	V
Low Level Output	V_{OL}	I_{OUT} = 100μA, 3.3MHz	0	-	0.1×V_{DD}	V
Operating Current for V_{DD}	I_{DD}		-	180	300	μA
Operating Current for V_{DDB} (V_{CC} Generated by Internal DC/DC)	I_{DDB}	Note 10	-	12.5	15.6	mA
		Note 11	-	17.8	22.3	mA
		Note 12	-	27.9	34.9	mA
Sleep Mode Current for V_{DD}	$I_{DD, SLEEP}$		-	1	5	μA
Sleep Mode Current for V	I		-	2	10	μA

Note 9: Brightness (L) and Supply Voltage for Display (V) are subject to the change of the panel characteristics and the customer's request.

Note 10: V_{DD} = 2.8V, V_{DDB} = 3.5V, 30% Display Area Turn on.
Note 11: V_{DD} = 2.8V, V_{DDB} = 3.5V, 50% Display Area Turn on.
Note 12: V_{DD} = 2.8V, V_{DDB} = 3.5V, 100% Display Area Turn on.

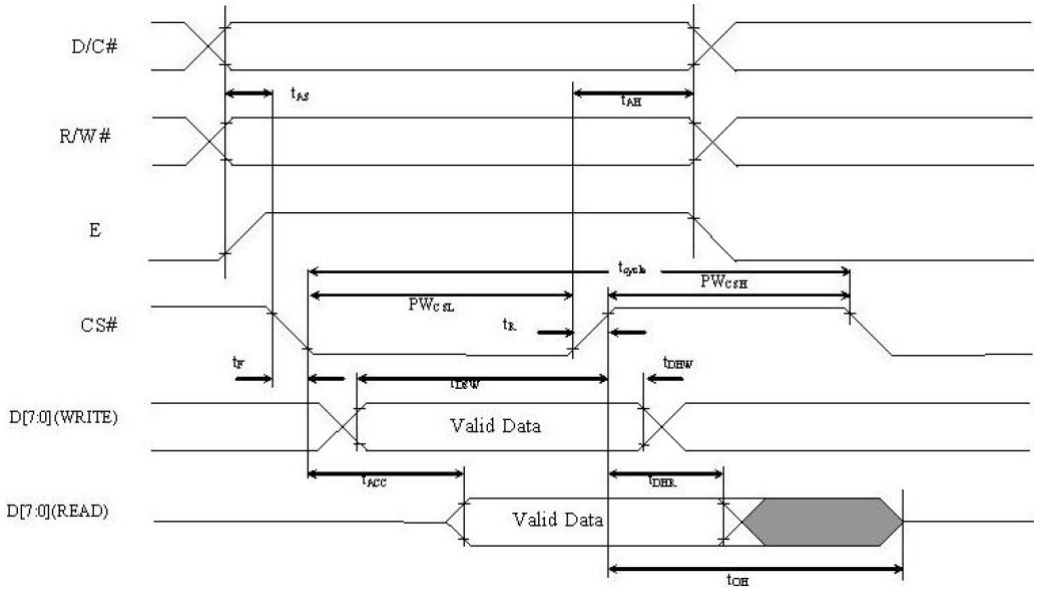
* Software configuration follows Section 4.5.2 Initialization.

3.3 AC Characteristics

3.3.1 68XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	ns
t_{AS}	Address Setup Time	5	-	ns
t_{AH}	Address Hold Time	0	-	ns
t_{DSW}	Write Data Setup Time	40	-	ns
t_{DHW}	Write Data Hold Time	7	-	ns
t_{DHR}	Read Data Hold Time	20	-	ns
t_{OH}	Output Disable Time	-	70	ns
t_{ACC}	Access Time	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (Read)	120	-	ns
	Chip Select Low Pulse width (Write)	60		
PW_{CSH}	Chip Select High Pulse Width (Read)	60	-	ns
	Chip Select High Pulse Width (Write)	60		
t_R	Rise Time	-	40	ns
t_F	Fall Time	-	40	ns

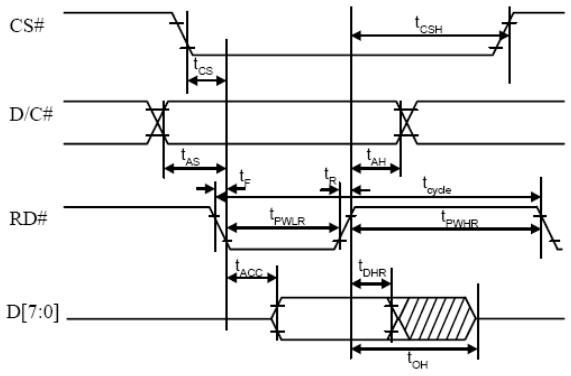
* (V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)



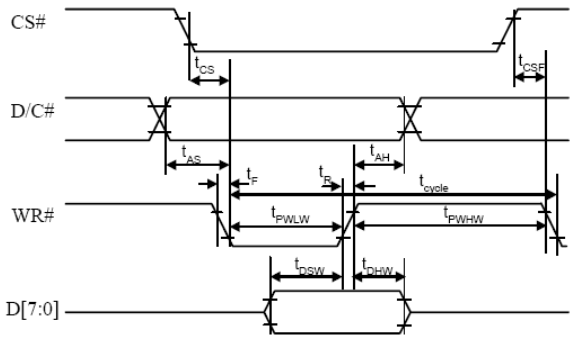
3.3.2 80XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	ns
t_{AS}	Address Setup Time	10	-	ns
t_{AH}	Address Hold Time	0	-	ns
t_{DSW}	Write Data Setup Time	40	-	ns
t_{DHW}	Write Data Hold Time	7	-	ns
t_{DHR}	Read Data Hold Time	20	-	ns
t_{OH}	Output Disable Time	-	70	ns
t_{ACC}	Access Time	-	140	ns
t_{PWLR}	Read Low Time	120	-	ns
t_{PWLW}	Write Low Time	60	-	ns
t_{PWHR}	Read High Time	60	-	ns
t_{PWHW}	Write High Time	60	-	ns
t	Chip Select Setup Time	0	-	ns
t_{CSH}	Chip Select Hold Time to Read Signal	0	-	ns
t_{CSF}	Chip Select Hold Time	20	-	ns
t_R	Rise Time	-	40	ns
t_F	Fall Time	-	40	ns

* (V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)



(***Read Timing***)

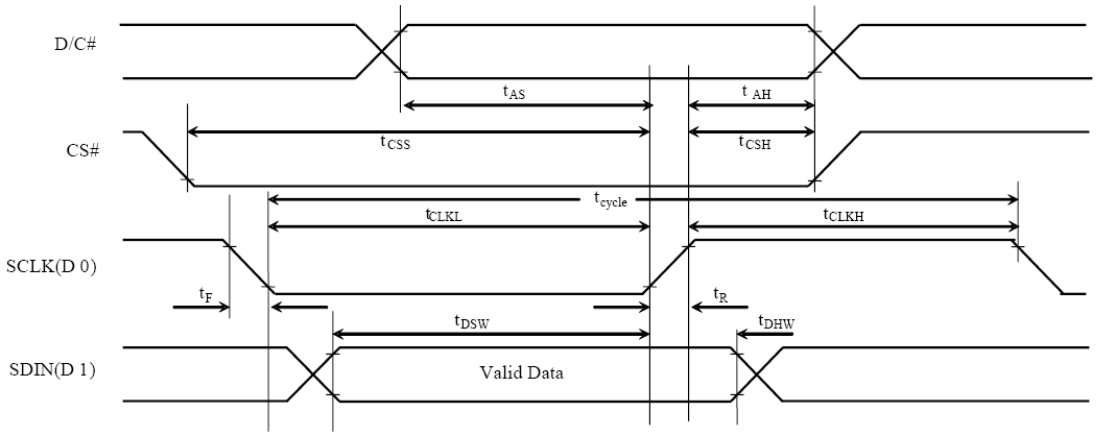


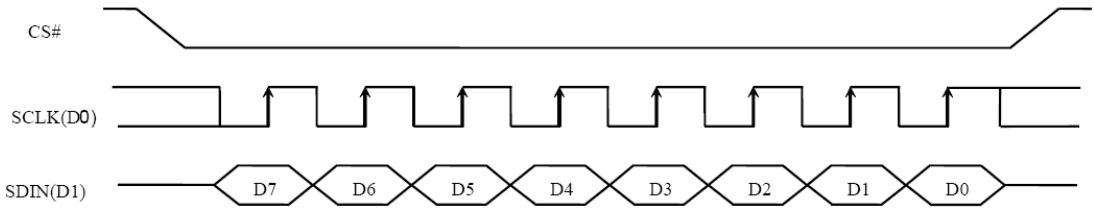
(***Write Timing***)

3.3.3 Serial Interface Timing Characteristics: (4-wire Serial)

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	ns
t_{AS}	Address Setup Time	15	-	ns
t_{AH}	Address Hold Time	15	-	ns
t_{CSS}	Chip Select Setup Time	20	-	ns
t_{CSH}	Chip Select Hold Time	10	-	ns
t_{DSW}	Write Data Setup Time	15	-	ns
t_{DHW}	Write Data Hold Time	15	-	ns
t_{CLKL}	Clock Low Time	20	-	ns
t_{CLKH}	Clock High Time	20	-	ns
t_R	Rise Time	-	40	ns
t_F	Fall Time	-	40	ns

* (V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)

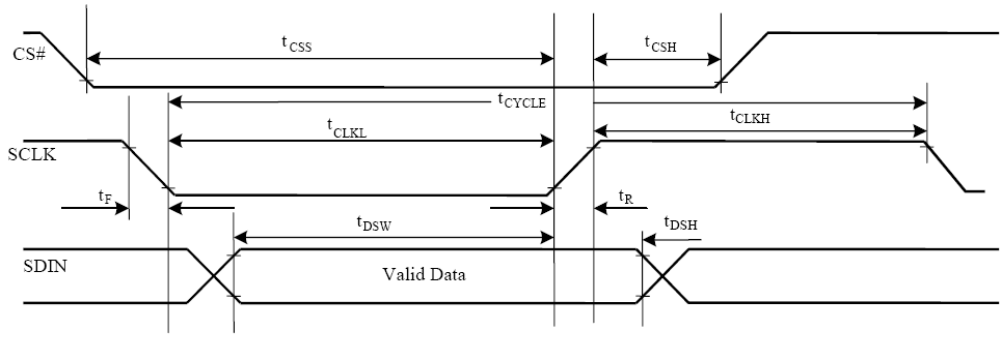


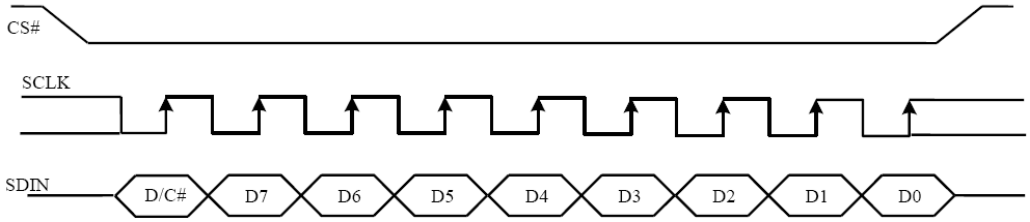


3.3.4 Serial Interface Timing Characteristics: (3-wire Serial)

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	100	-	ns
t_{CSS}	Chip Select Setup Time	20	-	ns
t_{CSH}	Chip Select Hold Time	10	-	ns
t_{DSW}	Write Data Setup Time	15	-	ns
t_{DHW}	Write Data Hold Time	15	-	ns
t_{CLKL}	Clock Low Time	20	-	ns
t_{CLKH}	Clock High Time	20	-	ns
t_R	Rise Time	-	40	ns
t_F	Fall Time	-	40	ns

* (V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)

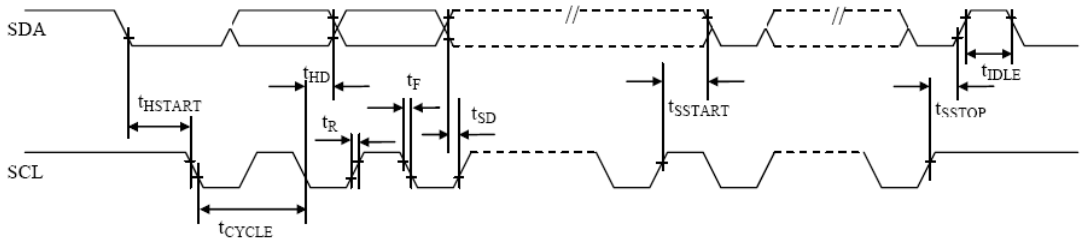




3.3.5 I^2C Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	2.5	-	μs
t_{HSTART}	Start Condition Hold Time	0.6	-	μs
t_{HD}	Data Hold Time (for "SDA_{OUT}" Pin)	0	-	ns
	Data Hold Time (for "SDA_{IN}" Pin)	300		
t_{SD}	Data Setup Time	100	-	ns
t_{SSTART}	Start Condition Setup Time (Only relevant for a repeated Start condition)	0.6	-	μs
t_{SSTOP}	Stop Condition Setup Time	0.6	-	μs
t_R	Rise Time for Data and Clock Pin		300	ns
t_F	Fall Time for Data and Clock Pin		300	ns
t_{IDLE}	Idle Time before a New Transmission can Start	1.3	-	μs

* (V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)



4. Functional Specification

4.1 Commands

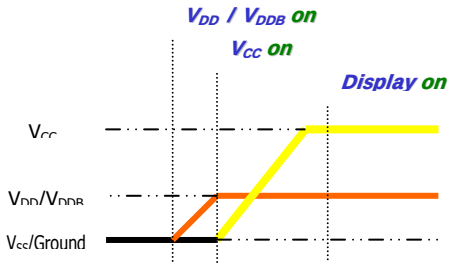
Refer to the Technical Manual for the SSD1306

4.2 Power down and Power up Sequence

To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

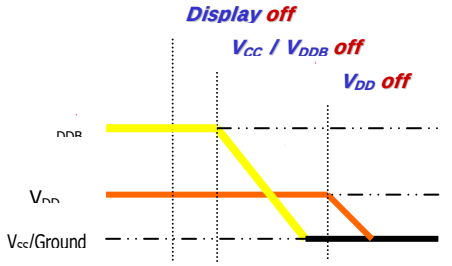
4.2.1 Power up Sequence:

1. Power up V_{DD} / V_{DDB}
2. Send Display off command
3. Initialization
4. Clear Screen
5. Power up V_{CC}
6. Delay 100ms
   (When V_{CC} is stable)
7. Send Display on command



4.2.2 Power down Sequence:

1. Send Display off command
2. Power down V
3. Delay 100ms
   (When V_{CC} / V_{DDB} is reach 0 and panel is completely discharges)
4. Power down V_{DD}



Note 13:

1) Since an ESD protection circuit is connected between V_{DD} and V_{CC} inside the driver IC, V_{CC} becomes lower than V_{DD} whenever V_{DD} is ON and V_{CC} is OFF.
2) V_{CC} / V_{DDB} should be kept float (disable) when it is OFF.
3) Power Pins (V_{DD}, V_{CC}, V_{DDB}) can never be pulled to ground under any circumstance.
4) V_{DD} should not be power down before V_{CC} / V_{DDB} power down.

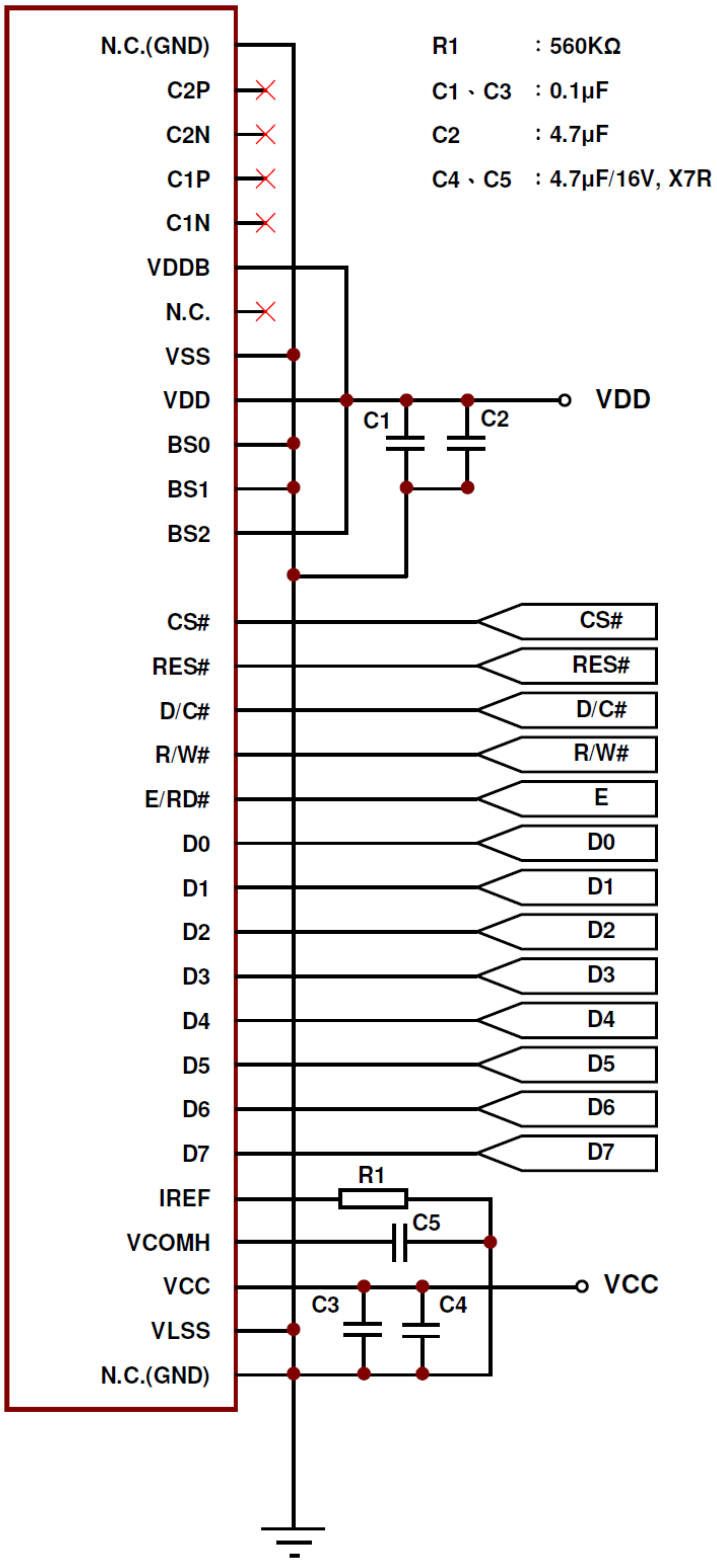
4.3 Reset Circuit

When RES# input is low, the chip is initialized with the following status:

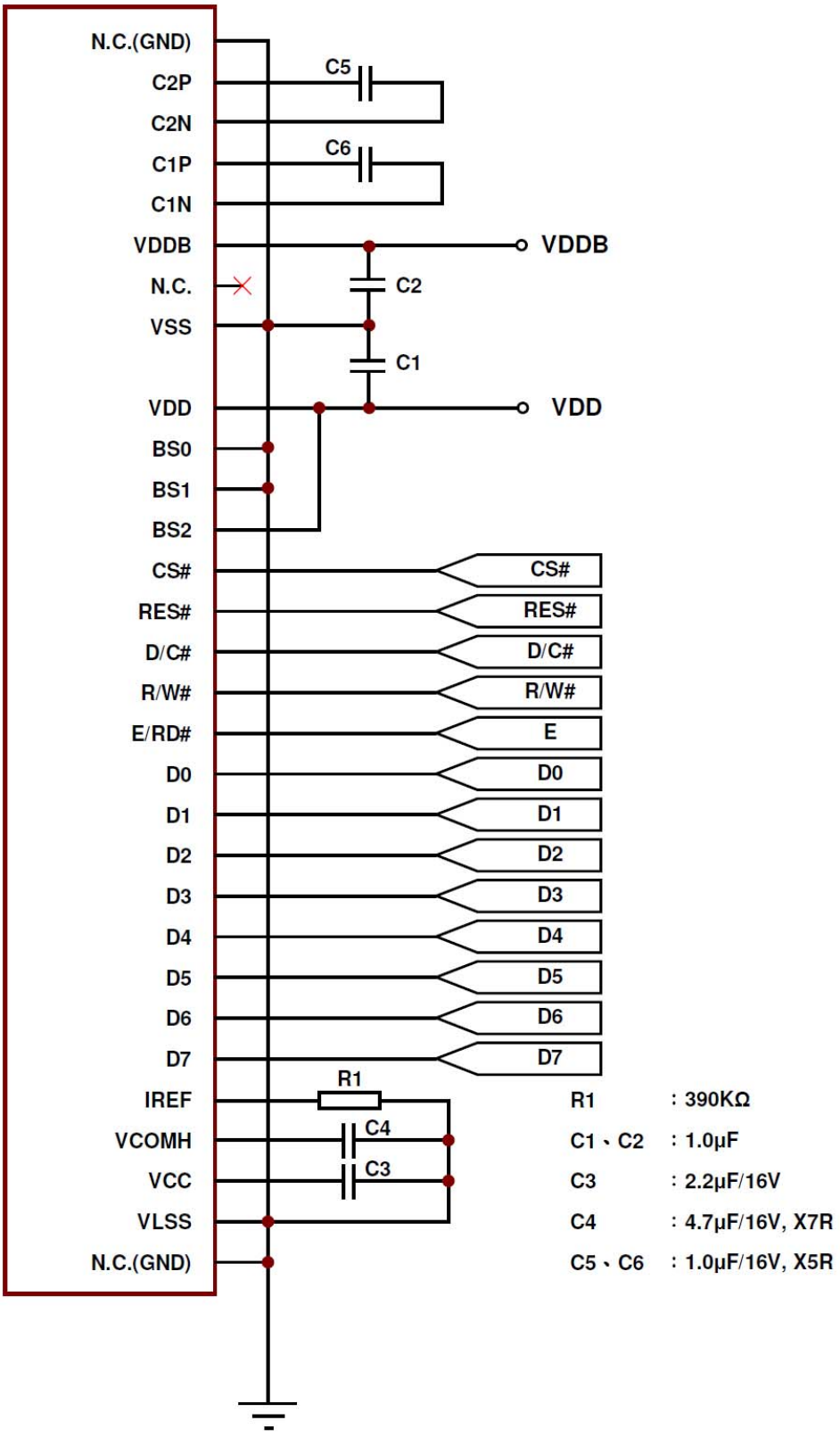
1. Display is OFF
2. 128×64 Display Mode
3. Normal segment and display data column and row address mapping (SEG0 mapped to column address 00h and COM0 mapped to row address 00h)
4. Shift register data clear in serial interface
5. Display start line is set at display RAM address 0
6. Column address counter is set at 0
7. Normal scan direction of the COM outputs
8. Contrast control register is set at 7Fh
9. Normal display mode (Equivalent to A4h command)

4.4 Application circuit

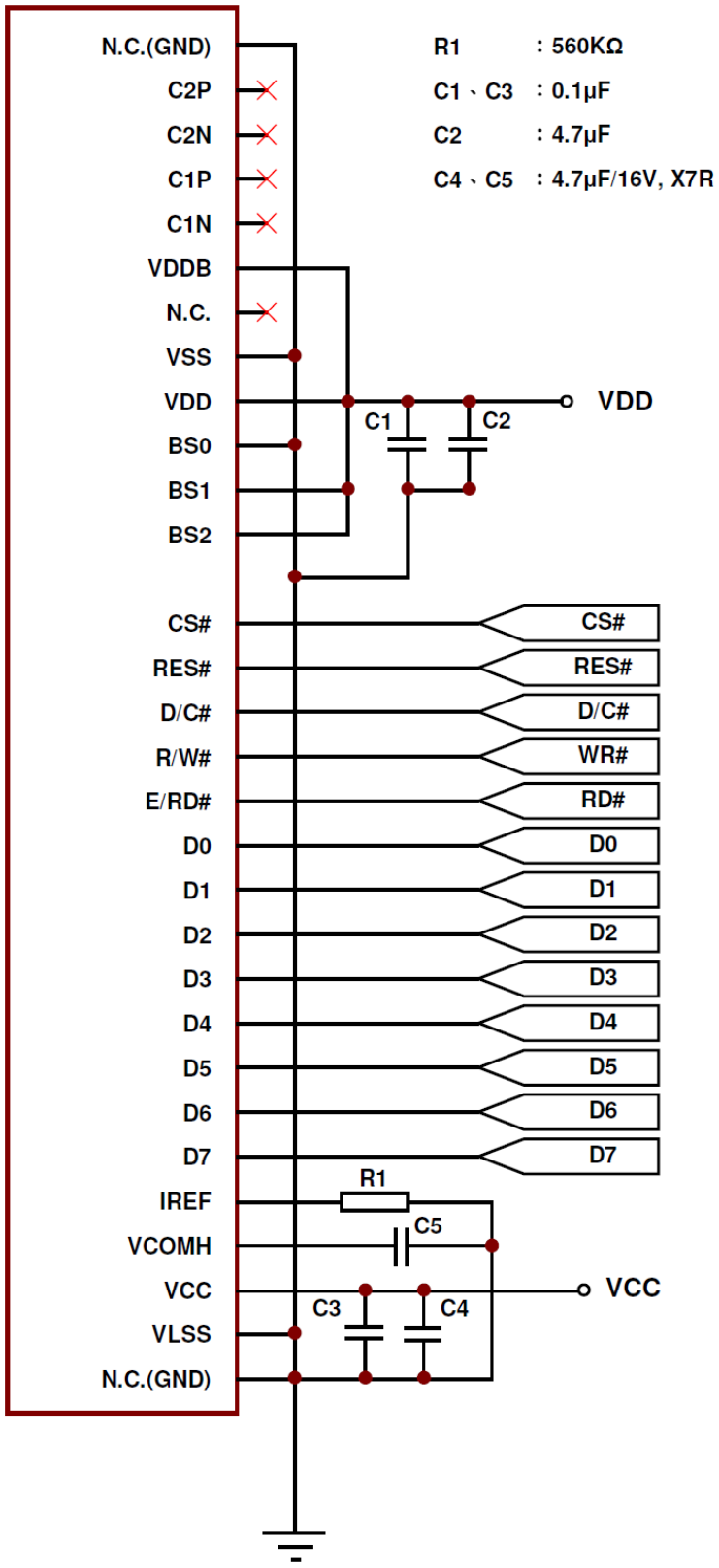
4.4.1 6800 parallel interface with V_{CC} Supplied Externally



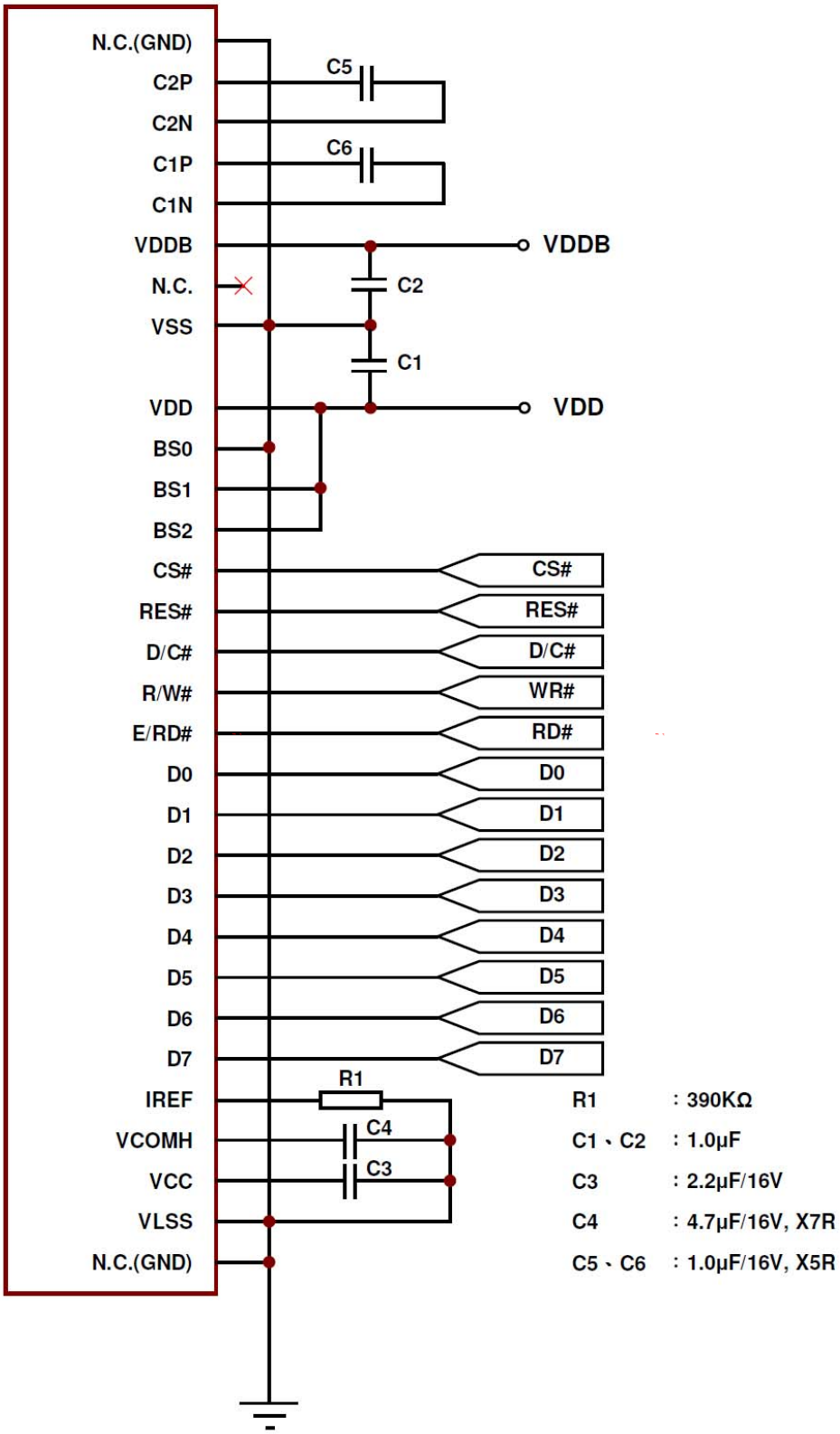
4.4.2 6800 parallel interface with V_{CC} Generated by Internal DC/DC Circuit



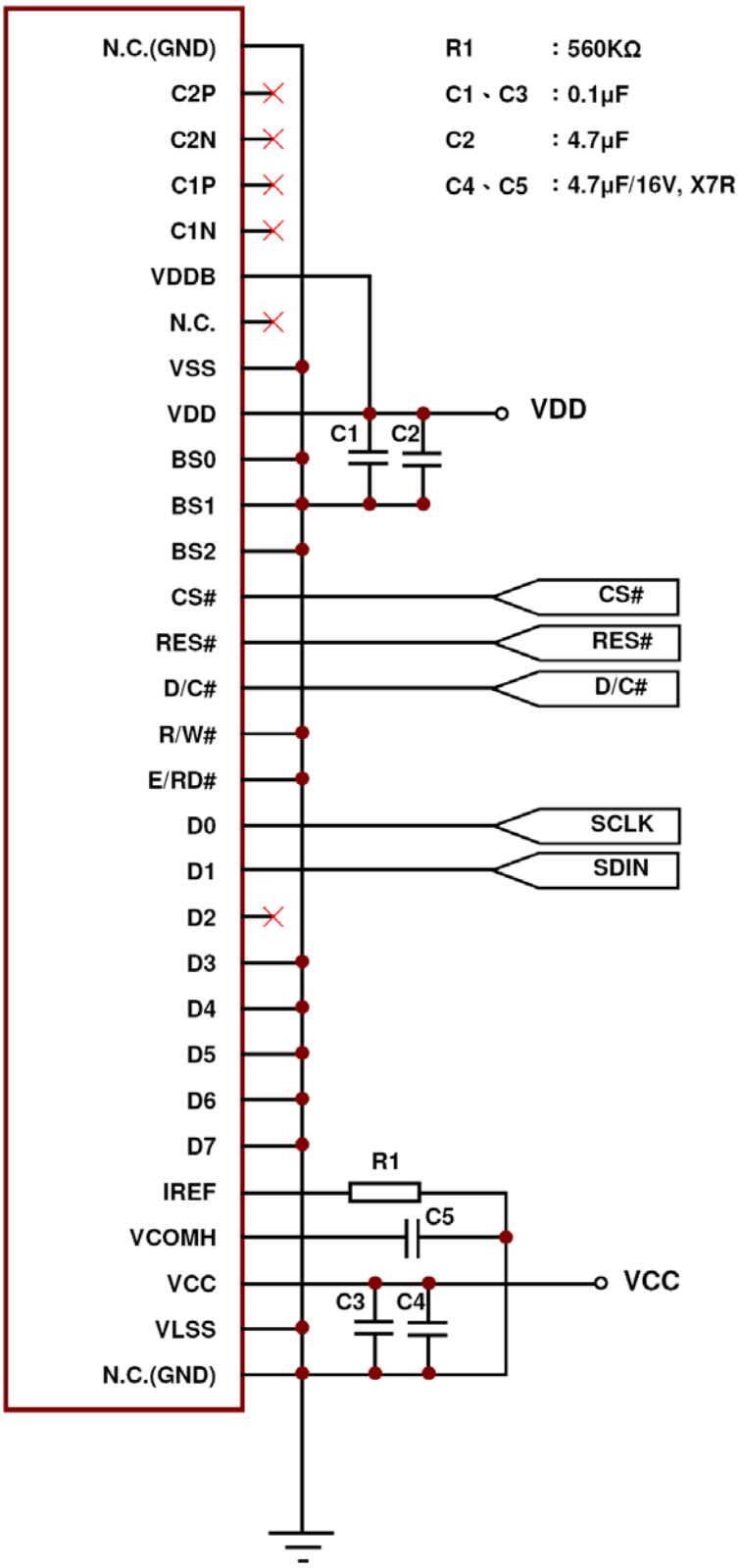
4.4.3 8080 parallel interface with V_{CC} Supplied Externally



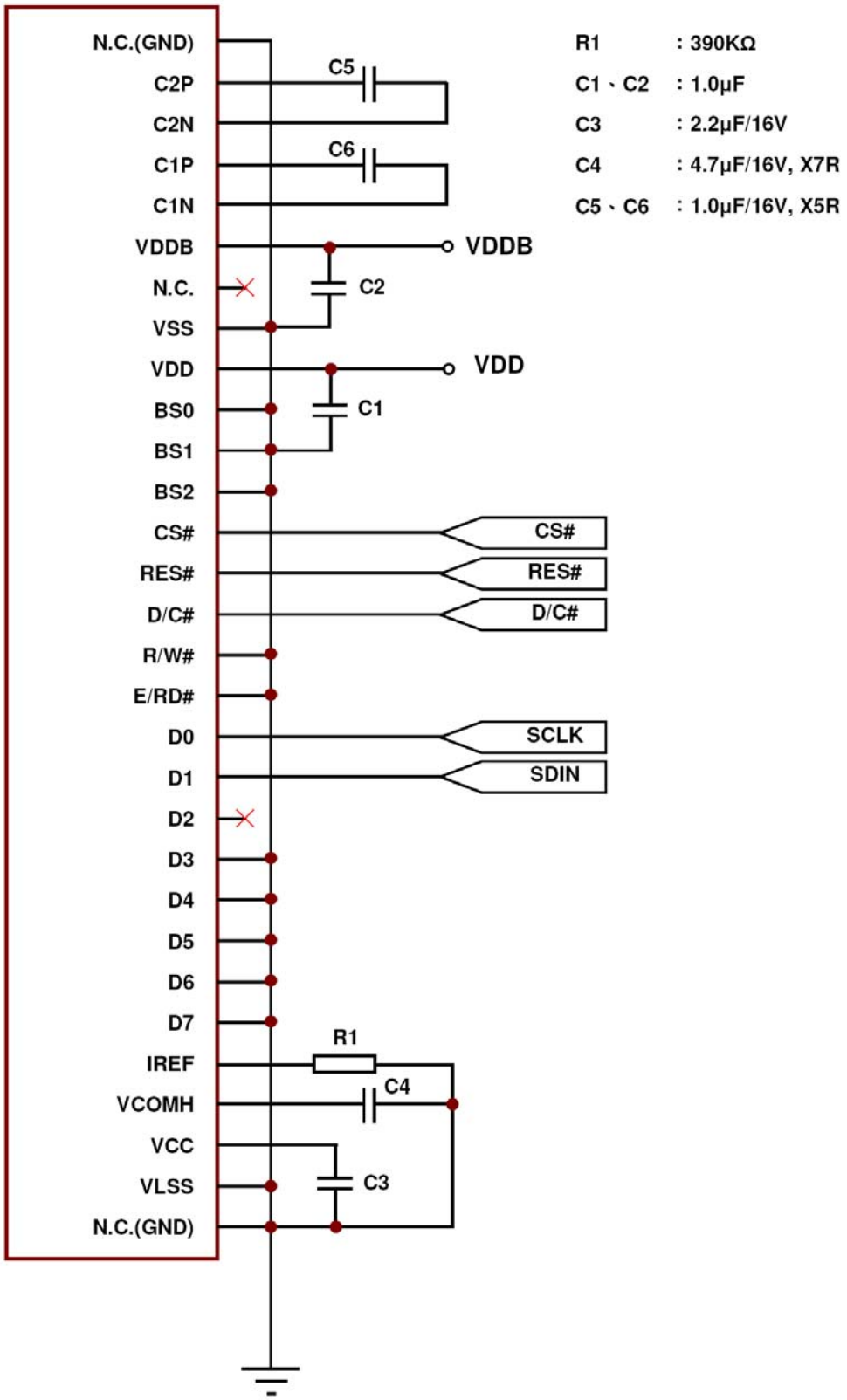
4.4.4 8080 parallel interface with V_{CC} Generated by Internal DC/DC Circuit



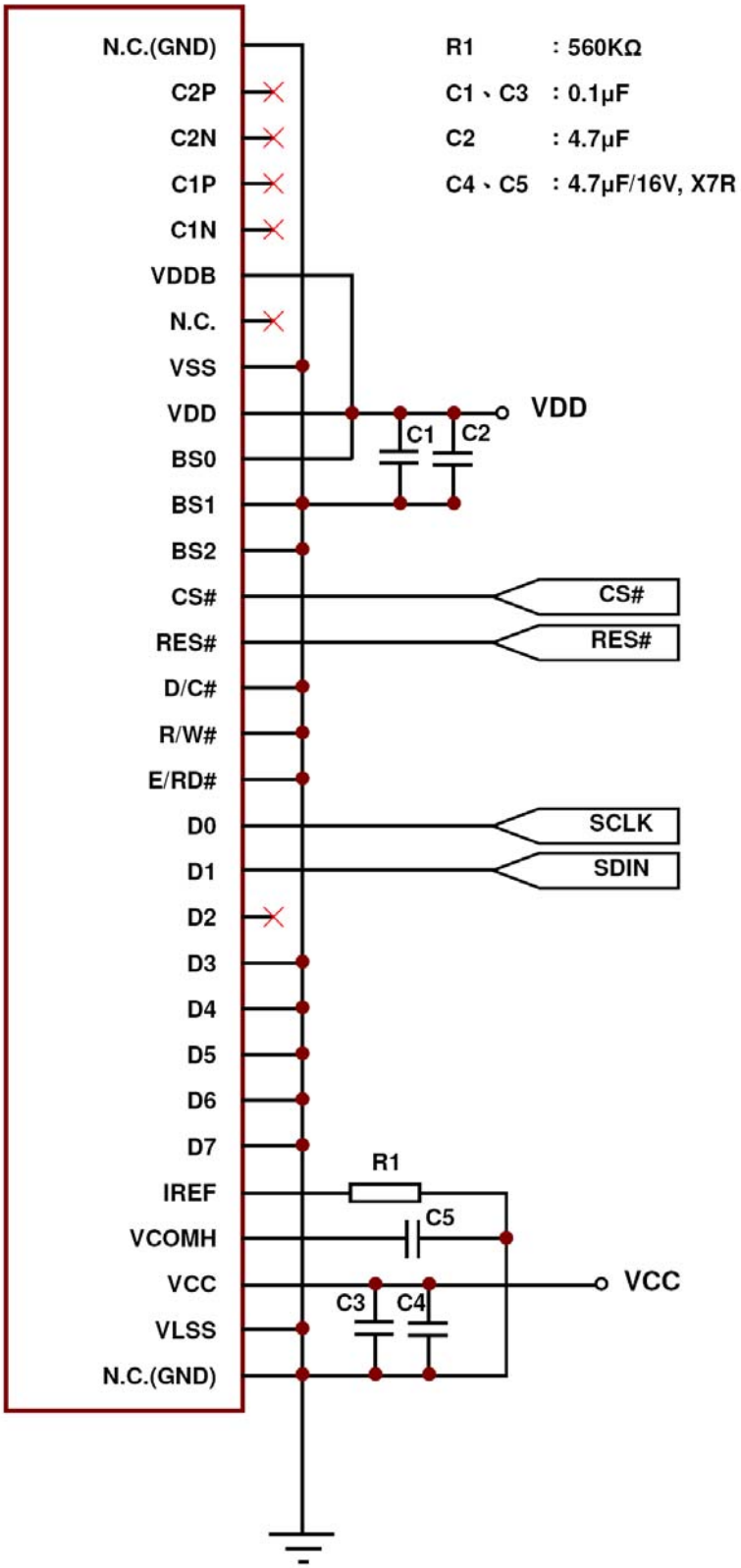
4.4.5 4-wire SPI interface with V_{CC} Supplied Externally



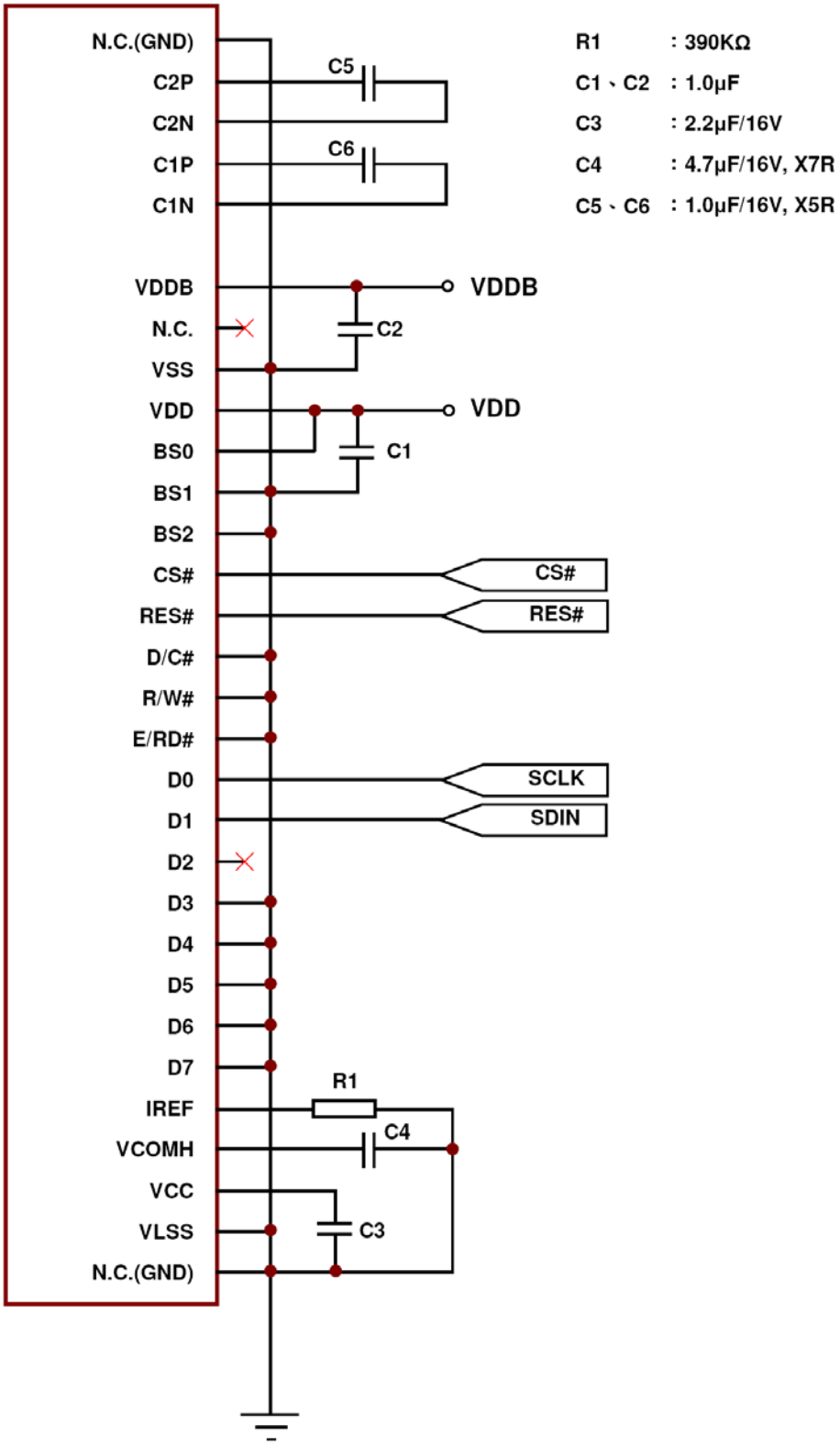
4.4.6 4-wire SPI interface with V_{CC} Generated by Internal DC/DC Circuit



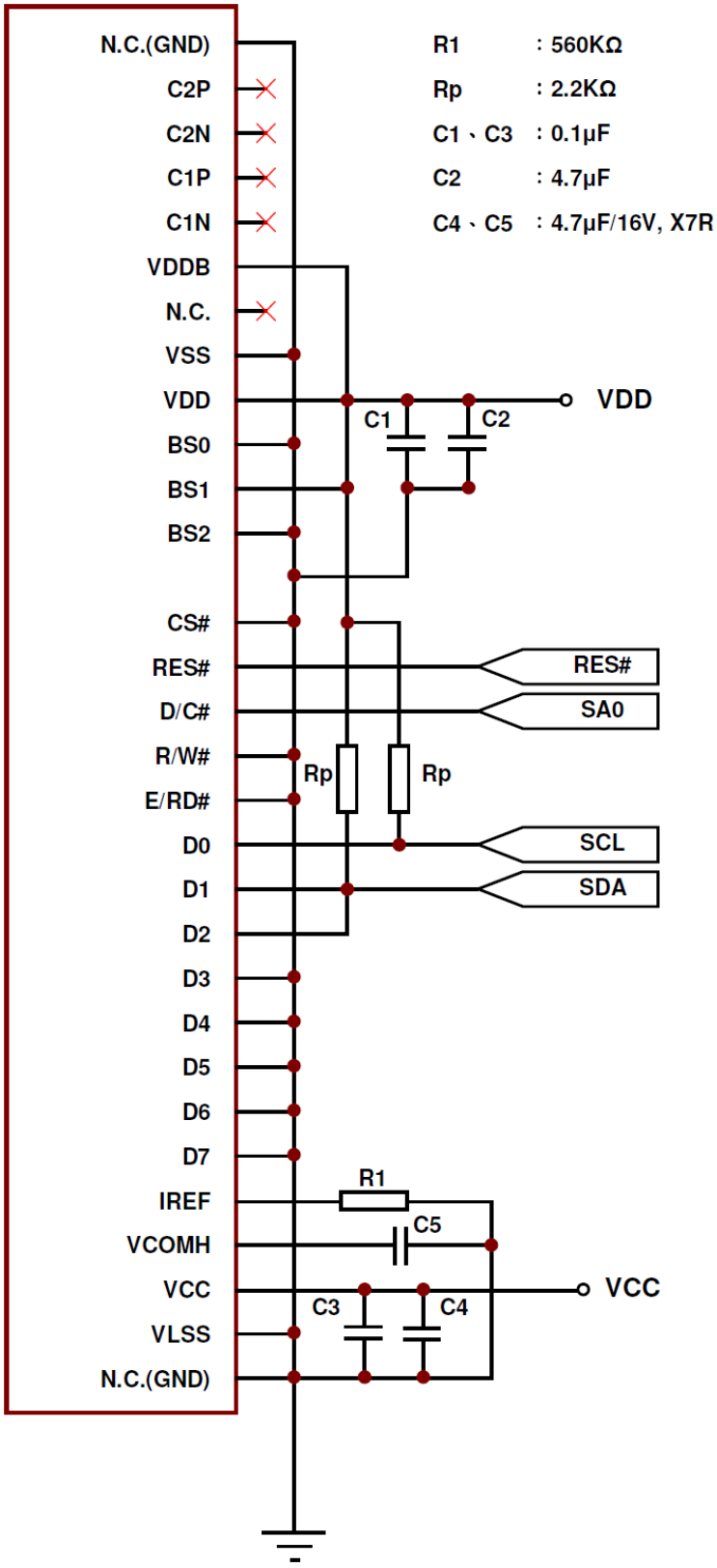
4.4.7 3-wire SPI interface with V_{CC} Supplied Externally



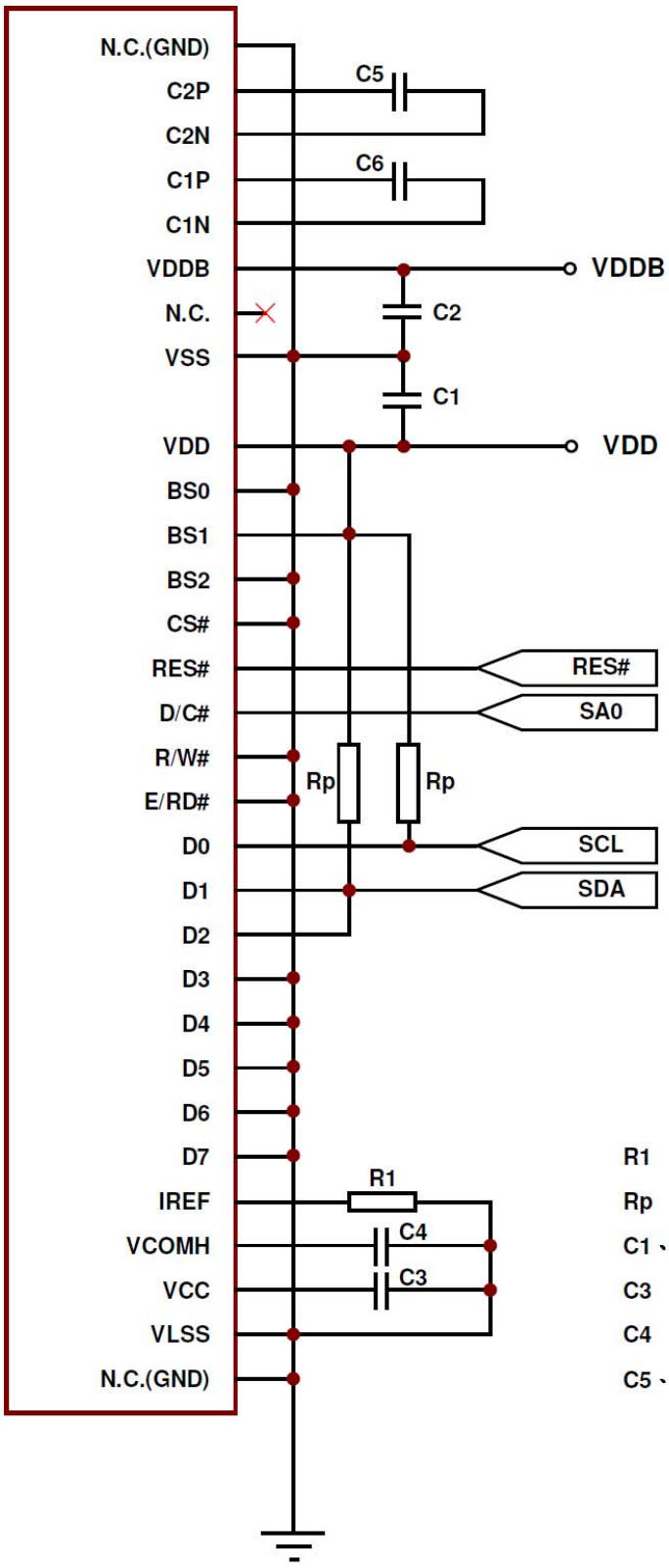
4.4.8 3-wire SPI interface with V_{CC} Generated by Internal DC/DC Circuit



4.4.9 I^2C interface with V_{CC} Supplied Externally



4.4.10 I^2C interface with V_{CC} Generated by Internal DC/DC Circuit



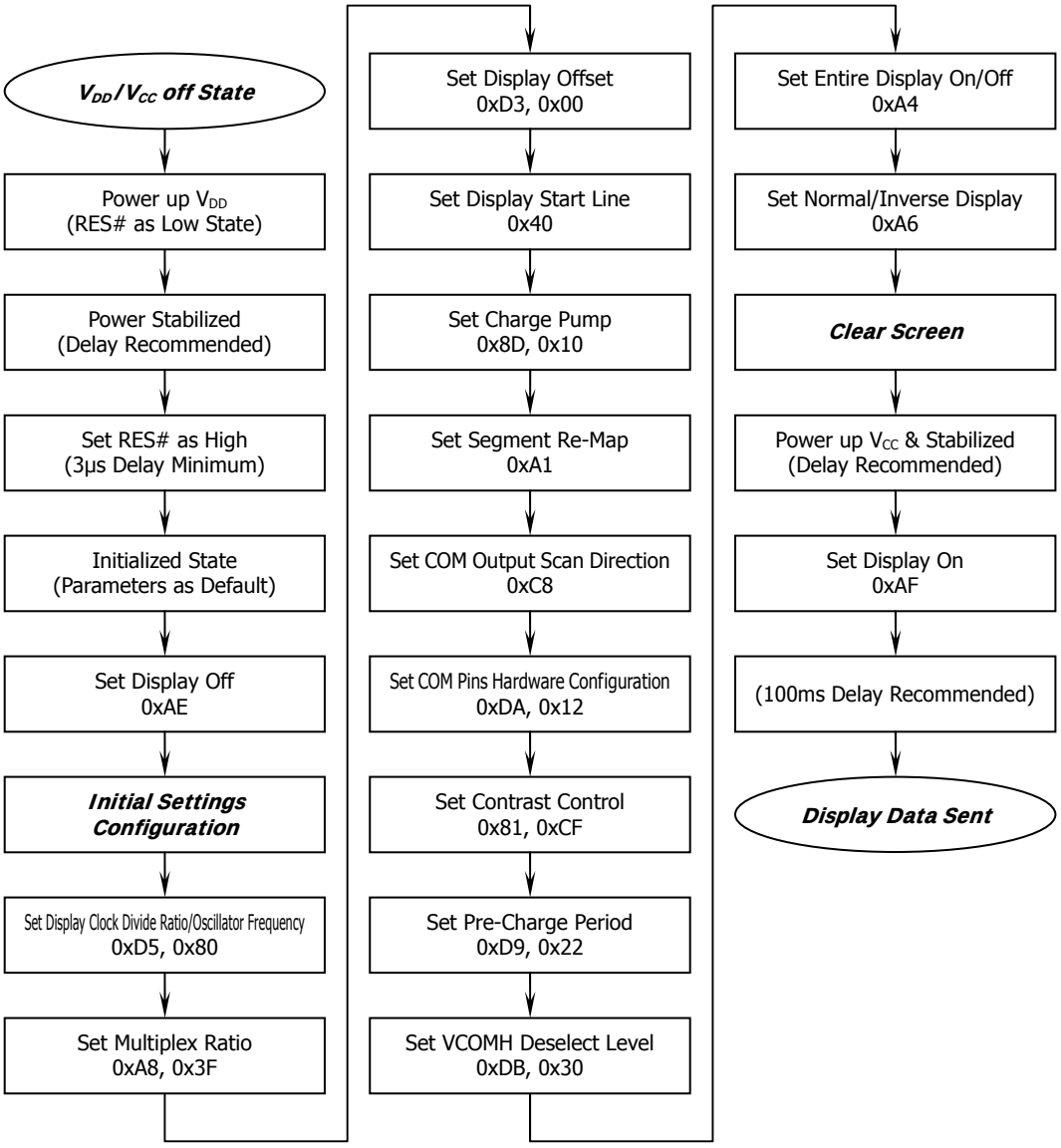
R1	: 390KΩ
Rp	: 2.2KΩ
C1、C2	: 1.0μF
C3	: 2.2μF/16V
C4	: 4.7μF/16V, X7R
C5、C6	: 1.0μF/16V, X5R

4.5 Actual Application Example

Command usage and explanation of an actual example

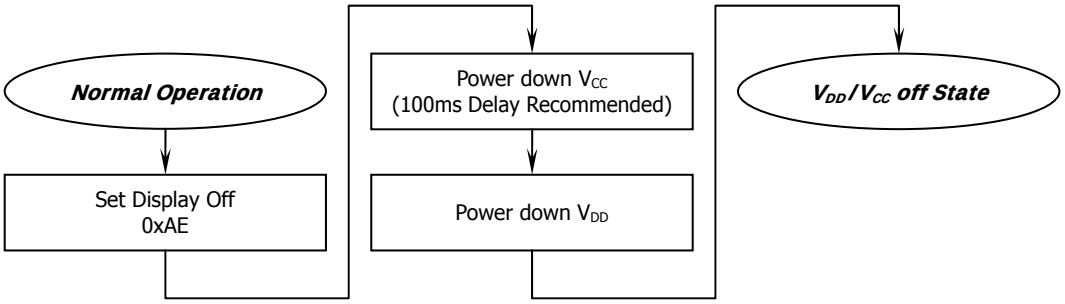
4.5.1 V_{CC} Supplied Externally

<Power up Sequence>

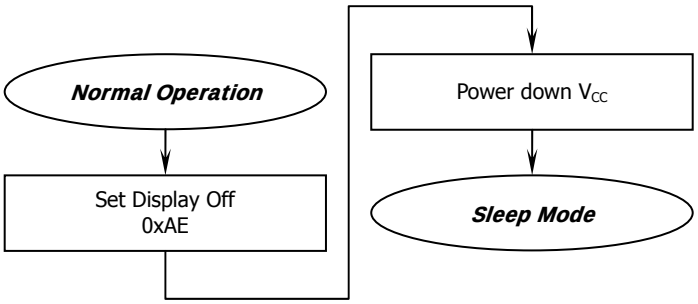


If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

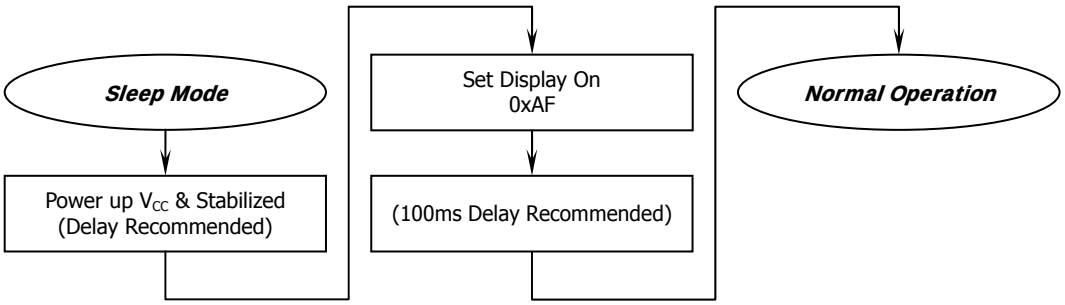
<Power down Sequence>



<Entering Sleep Mode>



<Exiting Sleep Mode>

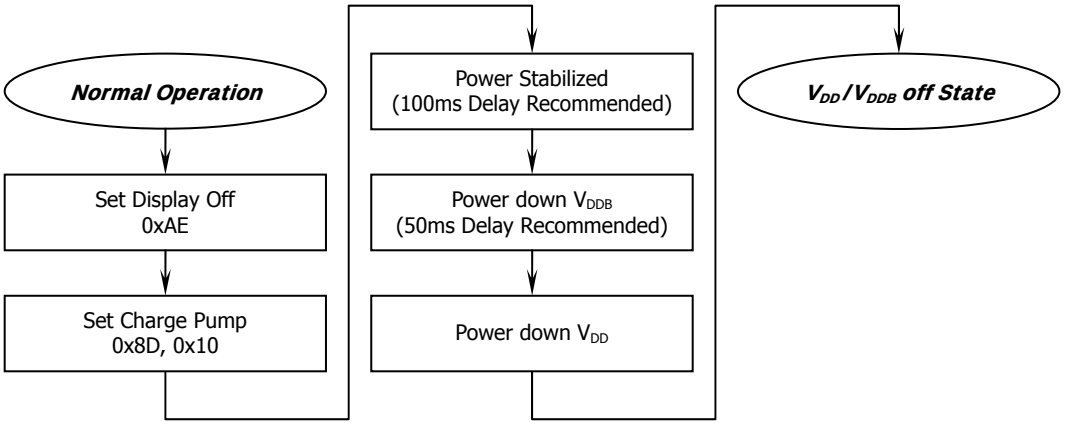


4.5.2 V_{CC} Generated by Internal DC/DC Circuit

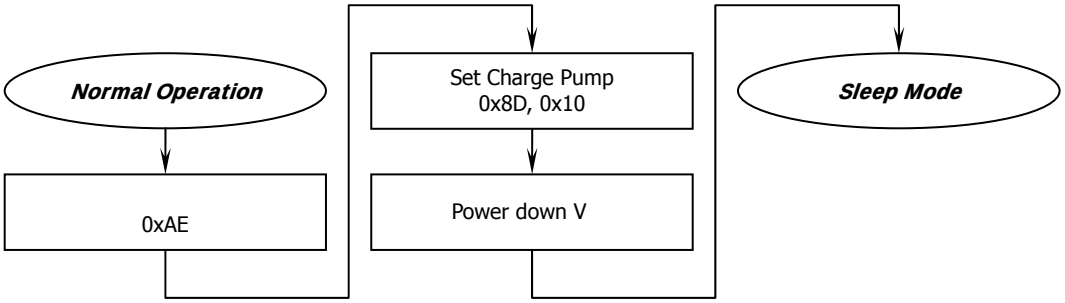
<Power up Sequence>

If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

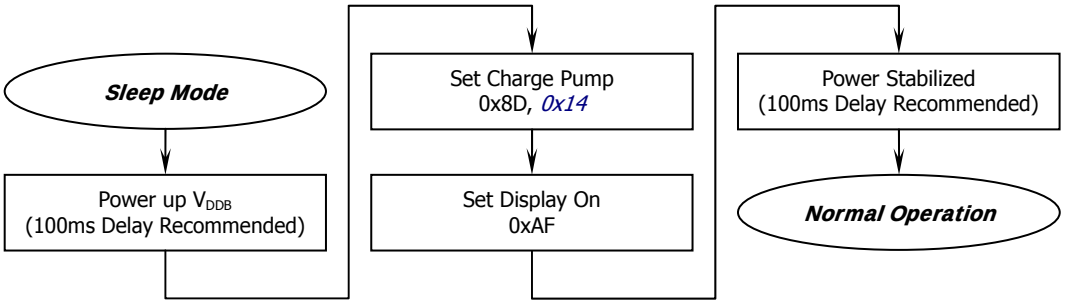
<Power down Sequence>



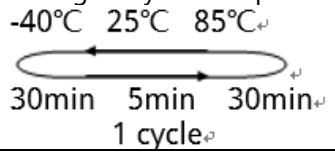
<Entering Sleep Mode>



<Exiting Sleep Mode>



5 Reliability

Test Item	Content of Test	Test Condition	Note
High Temperature Storage	Endurance test applying the high storage temperature for a long time.	85℃ 200hrs	2
Low Temperature Storage	Endurance test applying the high storage temperature for a long time.	-40℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	85℃ 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40 ℃ 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60℃,90%RH max, for 96hrs under no-load condition excluding the polarizer. Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal Shock Resistance	The sample should be allowed stand the following 10 cycles of operation  	-40℃/85℃ 10 cycles	-
Vibration Test	Endurance test applying the vibration during transportation and using	Total fixed amplitude: 15mm; Vibration: 10~55Hz; One cycle 60 seconds to 3 directions of X, Y, Z, for each 16 minutes.	3
Static Electricity Test	Endurance test apply the electric stress to the terminal.	VS=800V, RS=1.5kΩ, CS=100pF, 1 time.	-

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal. Temperature and humidity after remove from the rest chamber.

Note3: Test performed on product itself, not inside a container.

6 Warranty and Conditions

http://www.displaymodule.com/pages/faq